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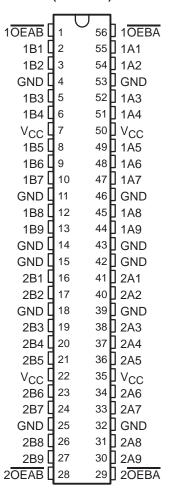
- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center **Spacings**

description

The 'ACT16864 are 18-bit inverting transceivers designed for asynchronous communication between data buses. The control-function implementation minimizes external requirements.

The 'ACT16864 can be used as two 9-bit transceivers or one 18-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the output-enable (OEAB or OEBA) inputs.

54ACT16864...DW PACKAGE 74ACT16864...DL PACKAGE (TOP VIEW)



The 74ACT16864 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16864 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16864 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each 9-bit section)

INP	UTS	ODEDATION					
OEAB	OEBA	OPERATION					
Н	L	B data to A bus					
L	Н	A data to B bus					
Н	Н	Isolation					

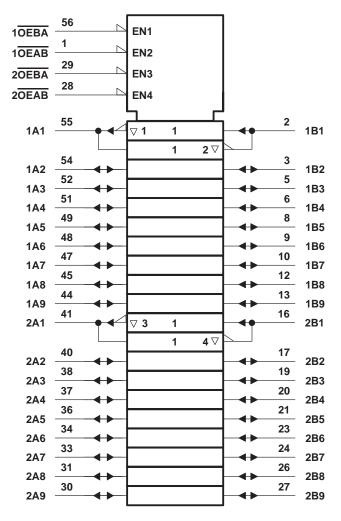


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logic symbol†

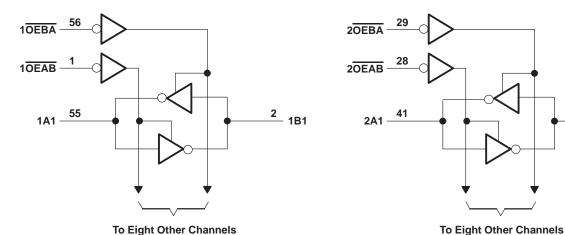


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



16 2B1

logic diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Note 1)–C	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±450 mA
Maximum package power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 3)

		54ACT16864		74ACT16864			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2	- 4	4	2			V
VIL	Low-level input voltage		0.8				0.8	V
٧ _I	Input voltage	0	W. W.	VCC	0		VCC	V
VO	Output voltage	0	7	VCC	0		VCC	V
loh	High-level output current	./(5	-24			-24	mA
loL	Low-level output current	⁷ 0į		24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V	T,	Δ = 25°C		54ACT	16864	74ACT	16864	UNIT	
		TEST CONDITIONS	v _{CC}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT	
		10.1 - 50.11A	4.5 V	4.4			4.4		4.4			
		I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4			
Vон		1011 - 24 mA	4.5 V	3.94			3.8		3.8		V	
		I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8			
		I _{OH} = -75 mA [†]	5.5 V				3.85		3.85			
		10 50 uA	4.5 V			0.1		0.1		0.1	V	
		I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1		
VOL		le: - 24 mA	4.5 V			0.36	4	0.44		0.44		
		I _{OL} = 24 mA	5.5 V			0.36	,C	0.44		0.44		
		I _{OL} = 75 mA [†]	5.5 V				70	1.65		1.65		
II	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1) Jy	±1		±1	μΑ	
loz‡	A or B ports	V _O = V _{CC} or GND	5.5 V			±0.5	_	±5		±5	μΑ	
Icc	_	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ	
ΔICC§		One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA	
Ci	Control inputs	V _I = V _{CC} or GND	5 V		4.5						pF	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		17						pF	

T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	T _A = 25°C			54ACT16864		74ACT16864		UNIT
PARAMETER	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	A or B	B or A	1.6	7	8.9	1.6	10.2	1.6	10.2	ns
^t PHL			3.7	8.1	10	3.7	11.3	3.7	11.3	
^t PZH	OEAB or OEBA	B or A	2.2	8.2	10.1	2.2	211.1	2.2	11.1	
^t PZL			3.1	10.2	12.4	3.1	13.8	3.1	13.8	ns
t _{PHZ}	OEAB or OEBA	B or A	5.1	8.6	10.1	5.1	10.8	5.1	10.8	ns
t _{PLZ}			5	8.3	9.7	2 5	10.3	5	10.3	115

operating characteristics, V_{CC} = 5 V, T_A = 25°C

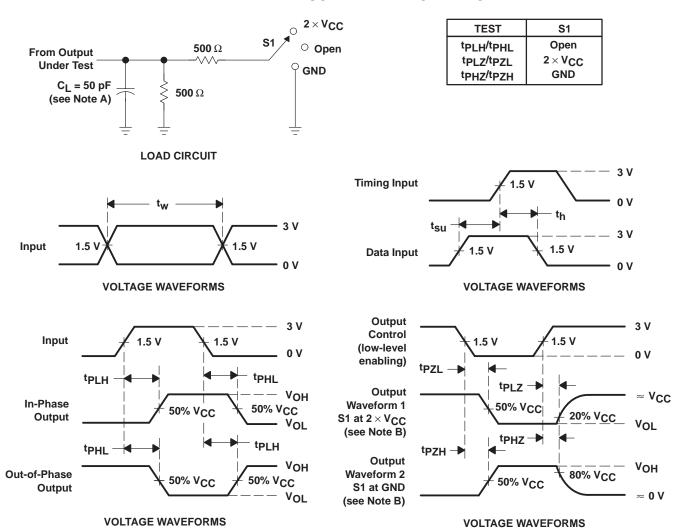
PARAMETER			TEST COI	TYP	UNIT	
C _{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C _I = 50 pF,	f = 1 MHz	56	pF
		Outputs disabled	OL = 30 pr,	1 – 1 1011 12	9	



[‡] For I/O ports, the parameter IOZ includes the input leakage current.

[§] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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